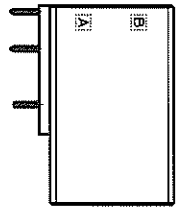
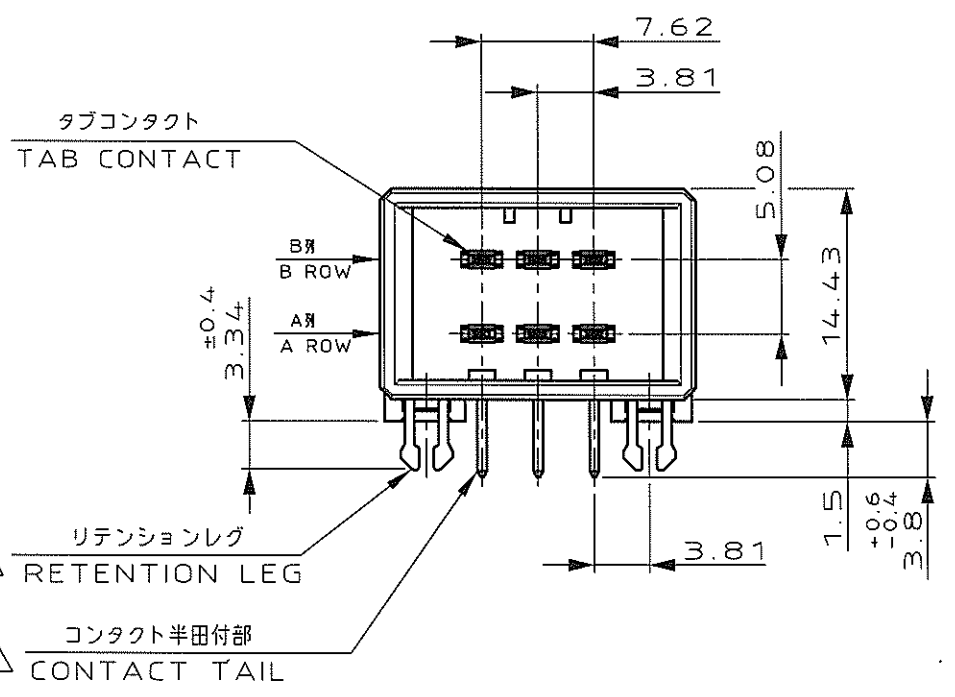
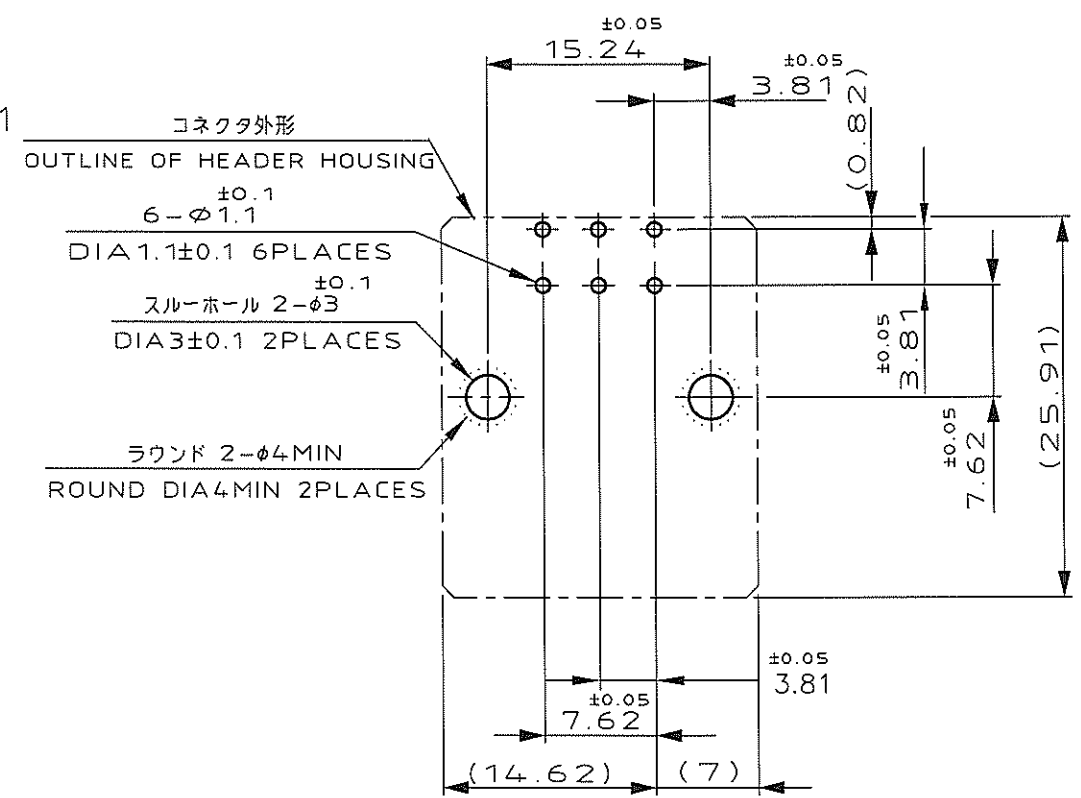
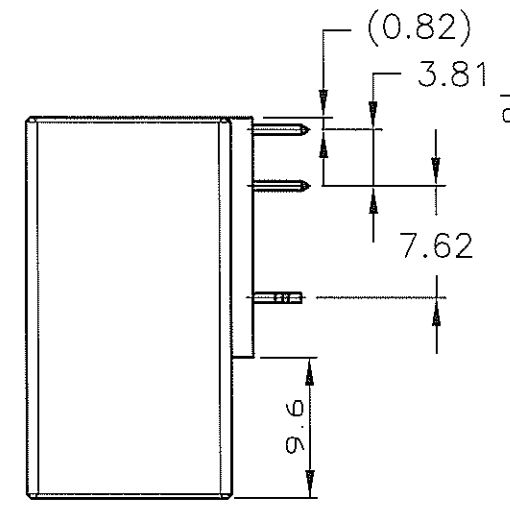
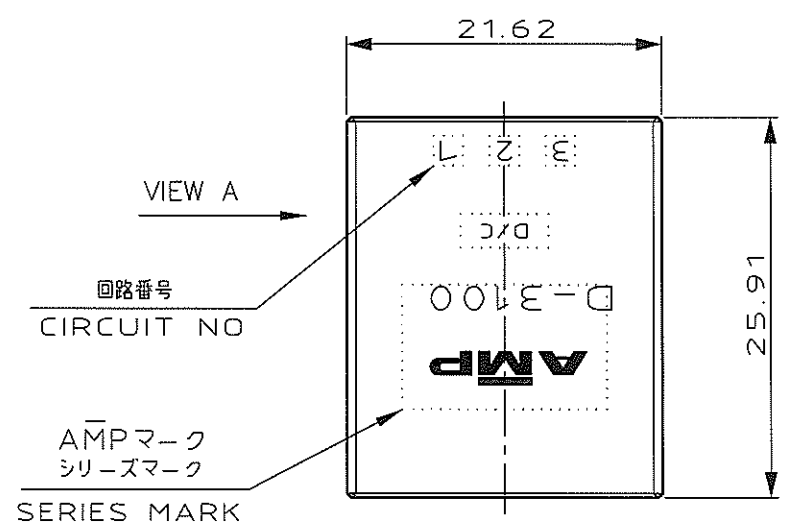


NUMBER 178303
 METRIC
 PRINT DIST
 DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT



推奨基板取付け穴寸法
 PC 基板厚: 1.6 ± 0.1
 (非累積公差)
 (コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
 PC BOARD THICKNESS: 1.6 ± 0.1
 (NOT ACCUMULATE TOLERANCE)
 (CONNECTOR MOUNT SIDE)

NOTES

1. MATERIAL: HOUSING: GLASS FILED THERMO PLASTIC, POLYESTER
 CONTACT: COPPER ALLOY
 RETENTION LEG: COPPER ALLOY
2. FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
3. FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
4. FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
5. FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
6. FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

1. 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
 コネクタ: 銅合金
 リテンションレグ: 銅合金
2. めっき: コネクタ: 全面Ni下地
 接触部: 0.38 μm MIN金めっき
3. めっき: コネクタ: 全面Ni下地
 接触部: 0.76 μm MIN金めっき
4. めっき: コネクタ: 全面Ni下地
 接触部: 2.0 μm MINスズめっき
5. めっき: リテンションレグとコンタクト半田付部
 ニッケル下地の上に半田めっき
6. めっき: リテンションレグとコンタクト半田付部 : ニッケル下地の上にスズめっき

△6	△4	178303-5
△6	△3	178303-3
△6	△2	178303-2
(FINISH)	製品番号 (PART NO.)	

C1	REVISED (ECR-07-013273)	TS	DM	11/20/91
C	REVISED (FJDO-0039-03)	TS	S.M	6/2/93
B	REVISED (FJDO-0097-03)	TS	S.M	4/15/93
A	REVISED (FJ00-2183-95)	KI	SM	3-23/95
O	RELEASED (J-1184)	NM	H.O	3-4/92
LTR	REVISION RECORD	DR	CHK	DATE

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WIRE RANGE	INSULATION DIA	NAME	ダイナミック D3100 水平タイプ 6 極 ヘッダーアセンブリ
MATERIAL	FINISH	一般公差 (GENERAL TOLERANCE)	SIZE LOC NUMBER
DR. N. Matsubara	FINISH SEE NOTE	100% ±0.3	A3 J C-178303
CHK. N. Ootani	APP. S. MANABE	100% ±0.4	SCALE 2-1
		30% ±0.45	REV. C1
		角 度 ±3'	SHEET 1 OF 1

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